



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model

[List multiple models if applicable.]

HP EliteDisplay E231 23-inch LED Backlit Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		28
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		5
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 SCREW DRIVER	#2
Description #2	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Lay the Monitor on the desk, Unlock the 4 screws which fix the Bucket with the screw driver
2. Take out the bezel with tool
3. Take out the keypad PCBA with Screw Driver
4. Take out the bucket with hand.
5. Take out the Tape and Foil with hand.
6. Take out the LED light connector
7. Remove the FFC connector from Panel.
8. Chassis assembly and panel
9. Remove the Mylar from chassis
10. Unlock the 4 screws which fix the IF board to the chassis,
11. Unlock the 9 screws which fix the IF & Power, USB PCBA
12. Remove the Mylar sheet from chassis with hands
13. Get all PCB and wires
14. Lay the Stand on the desk.
15. Unlock the VESA plate by Crosshead screw driver
16. Unlock the lift cover by Crosshead screw driver
17. Part riser back cover by hand
18. Get the screw by Crosshead crewdriver
19. Part riser front cover by hand
20. Part cable clip cover by hand
21. Unlock the side cover L&R by Crosshead crewdriver
22. Part arm back cover by hand
23. Unlock the arm front cover by Crosshead crewdriver
24. Rive off rubber pad by hand
25. Unlock the base cover by Crosshead crewdriver

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).